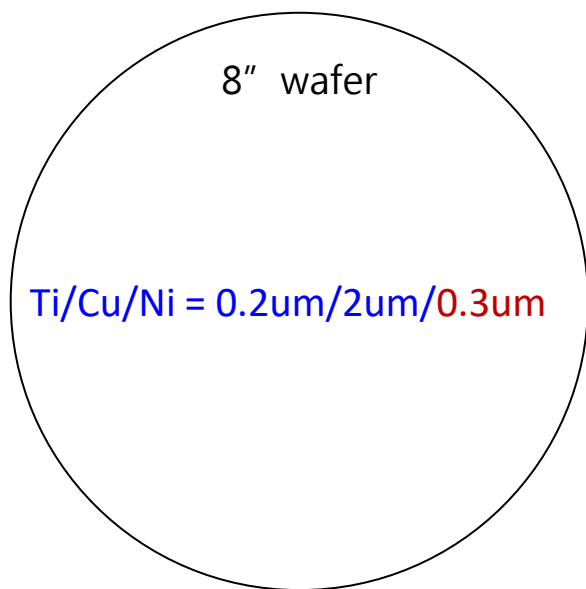


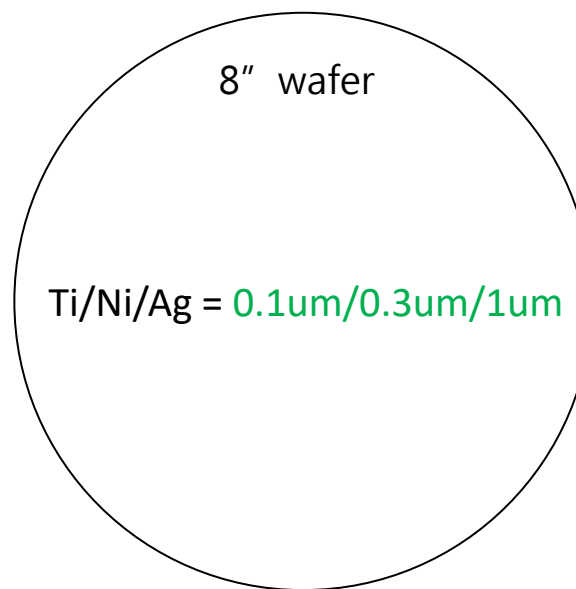
A512004138

## Sputter :

- Size : 8" Si wafer (750um)
- Sputter top metal :
  - (1) Ti/Cu/Ni = 0.2um/2um/0.3um → 需求2片
  - (2) Ti/Ni/Ag = 0.1um/0.3um/1um → 需求2片
- Bottom metal : none



需求 : 2片



需求 : 2片

- (1) 濺鍍Ti/Ni/Ag = 0.1um/0.3um/1um在離散元件上 (如下圖)
- (2) 但由於需要指區域濺鍍在top Exposed die (Silicon材)上 (2.3x4.47 mm藍色區域)
- (3) 需求數量 : 100pcs

